

### **NCE N-Channel Super Trench Power MOSFET**

#### **Description**

The series of devices uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{DS(ON)}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.

#### **Application**

- ●DC/DC Converter
- •Ideal for high-frequency switching and synchronous rectification

#### **General Features**

- $\bullet$ V<sub>DS</sub> =150V,I<sub>D</sub> =70A R<sub>DS(ON)</sub>=13.5mΩ (typical) @ V<sub>GS</sub>=10V
- ●Excellent gate charge x R<sub>DS(on)</sub> product(FOM)
- Very low on-resistance R<sub>DS(on)</sub>
- ●175 °C operating temperature
- Pb-free lead plating

100% UIS TESTED! 100% ΔVds TESTED!

**Schematic Diagram** 





**Package Marking and Ordering Information** 

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP1570	NCEP1570	TO-220			
NCEP1570D	NCEP1570D	TO-263	-	-	-

#### Absolute Maximum Ratings (T<sub>A</sub>=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	150	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous	I <sub>D</sub>	70	А
Drain Current-Continuous(T <sub>C</sub> =100 °C)	I <sub>D</sub> (100℃)	49	Α
Pulsed Drain Current	I <sub>DM</sub>	280	Α
Maximum Power Dissipation	P <sub>D</sub>	200	W
Derating factor		1.33	W/°C
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	672	mJ
Operating Junction and Storage Temperature Range	$T_{J}$ , $T_{STG}$	-55 To 175	$^{\circ}$

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# NCEP1570,NCEP1570D

#### **Thermal Characteristic**

**Electrical Characteristics (T<sub>A</sub>=25**°C unless otherwise noted)

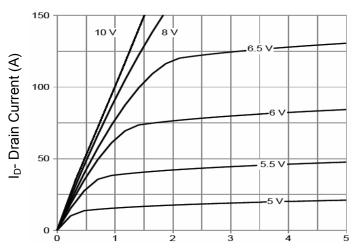
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	·					
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	150	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =150V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)			•			
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	2.0	3.1	4.0	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =35A	-	13.5	15	mΩ
Forward Transconductance	<b>g</b> FS	$V_{DS}$ =5 $V$ , $I_D$ =35 $A$	-	58	-	S
Dynamic Characteristics (Note4)	<u>.</u>		•	•		
Input Capacitance	C <sub>lss</sub>	\/ 75\/\/ 0\/	-	2000	-	PF
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ =75 $V$ , $V_{GS}$ =0 $V$ ,	-	280	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0MHz	-	16	-	PF
Switching Characteristics (Note 4)			•			
Turn-on Delay Time	t <sub>d(on)</sub>		-	12.5	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =75V, $I_{D}$ =35A	-	3.8	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10 $V$ , $R_{G}$ =3 $\Omega$	-	14	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	3.5	-	nS
Total Gate Charge	Qg	\/ -75\/  -25A	-	35	-	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =75V, $I_{D}$ =35A, $V_{GS}$ =10V	-	11.8	-	nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =10V	-	9.9	-	nC
Drain-Source Diode Characteristics	<u>.</u>		•	•		
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =35A	-	-	1.2	V
Diode Forward Current (Note 2)	I <sub>S</sub>		-	-	70	Α
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> = 35A	-	105	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	160	-	nC

#### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec. The value of R<sub>BJA</sub> is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub> =25° C. the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- 5. E<sub>AS</sub> condition : Tj=25  $^{\circ}$ C,V<sub>DD</sub>=50V,V<sub>G</sub>=10V,L=0.5mH,Rg=25 $\Omega$

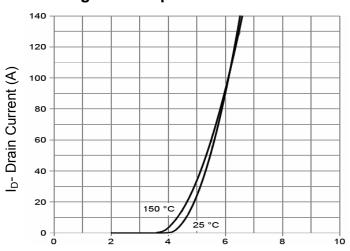


### **Typical Electrical and Thermal Characteristics**



Vds Drain-Source Voltage (V)

**Figure 1 Output Characteristics** 



Vgs Gate-Source Voltage (V)

**Figure 2 Transfer Characteristics** 

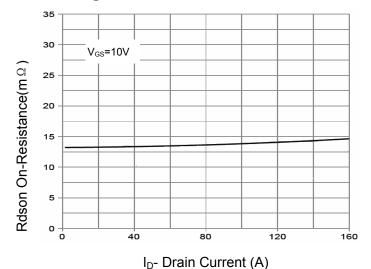
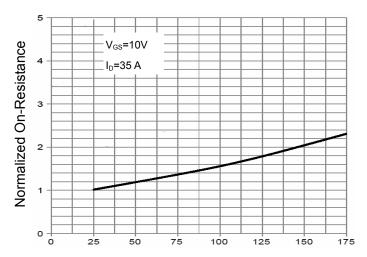


Figure 3 Rdson- Drain Current



T<sub>J</sub>-Junction Temperature(°C)

**Figure 4 Rdson-Junction Temperature** 

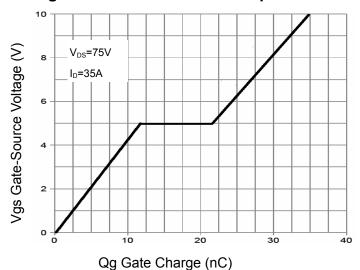
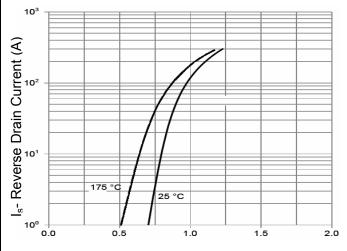


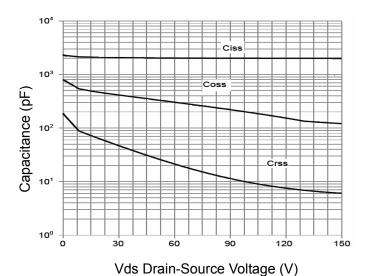
Figure 5 Gate Charge



Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward





Power Dissipation (W) 80 40 100

200

160

120

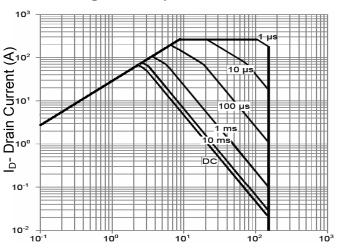
0+

 $T_J$ -Junction Temperature( $^{\circ}$ C)

200

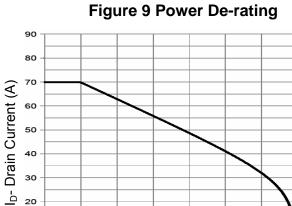
200

Figure 7 Capacitance vs Vds



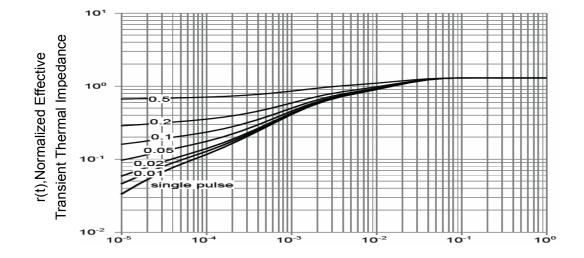
Vds Drain-Source Voltage (V)

Figure 8 Safe Operation Area



 $T_J$ -Junction Temperature ( $^{\circ}$ C)

Figure 10 Current De-rating

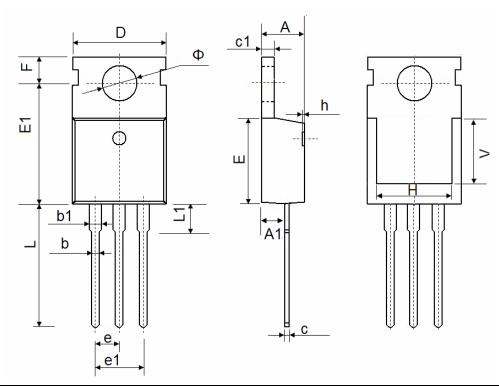


Square Wave Pluse Duration(sec)

**Figure 11 Normalized Maximum Transient Thermal Impedance** 



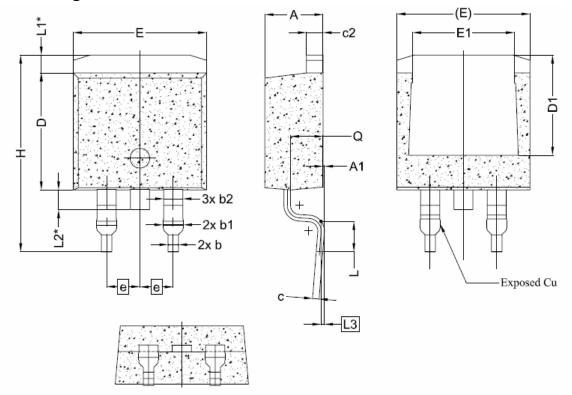
# **TO-220-3L Package Information**



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	4.400	4.600	0.173	0.181	
A1	2.250	2.550	0.089	0.100	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.330	0.650	0.013	0.026	
c1	1.200	1.400	0.047	0.055	
D	9.910	10.250	0.390	0.404	
Е	8.9500	9.750	0.352	0.384	
E1	12.650	12.950	0.498	0.510	
е	2.540 TYP.		0.100 TYP.		
e1	4.980	5.180	0.196	0.204	
F	2.650	2.950	0.104	0.116	
Н	7.900	8.100	0.311	0.319	
h	0.000	0.300	0.000	0.012	
L	12.900	13.400	0.508	0.528	
L1	2.850	3.250	0.112	0.128	
V	6.900 REF. 0.276		REF.		
Ф	3.400	3.800	0.134	0.150	



## **TO-263-2L Package Information**



Oh al	Dimensions In Millimeters			
Symbol	Min.	Nom.	Max.	
A	4.24	4.44	4.64	
A1	0.00	0.10	0.25	
b	0.70	0.80	0.90	
b1	1.20	1.55	1.75	
b2	1.20	1.45	1.70	
С	0.40	0.50	0.60	
c2	1.15	1.27	1.40	
D	8.82	8.92	9.02	
D1	6.86	7.65	-	
E	9.96	10.16	10.36	
E1	6.89	7.77	7.89	
е	2.54BSC			
Н	14.61	15.00	15.88	
L	1.78	2.32	2.79	
L1	1.36 REF.			
L2	1.50 REF.			
L3	0.25 BSC			
Q	2.30	2.48	2.70	

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# NCEP1570,NCEP1570D

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